



Attorney Docket No.: 5649-553DV

PATENT

6/C 2815
4/26/02
Mowish

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Hyae-Ryoung Lee

Group Art Unit: 2815

Serial No.: 09/800,138

Examiner: Paul E. Brock II

Filed: March 6, 2001

For: METHODS OF FORMING INTEGRATED BONDING PADS INCLUDNIG
CLOSED VIAS AND CLOSED CONDUCTIVE PATTERNS

Date: April 5, 2002

BOX NON-FEE AMENDMENT

Commissioner for Patents

Washington, DC 20231

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AMENDMENT

Sir:

This Amendment is responsive to the Official Action of February 6, 2002. The claims have been amended herein using the rewritten claims format. The present amendment also includes a section entitled "**VERSION WITH MARKINGS TO SHOW CHANGES MADE**" attached hereto.

In the Claims:

Please replace Claims 36, 37, and 39 with the following like numbered claims:

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36. (Amended) A method according to Claim 35 wherein the step of forming the conductive pattern comprises the step of forming a conductive pattern filling the closed via and on the dielectric layer opposite the substrate.

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37. (Amended) A method according to Claim 35 wherein the steps of forming the dielectric layer and forming the conductive pattern are repeatedly and sequentially performed to form a multilayer bonding pad on the integrated circuit substrate.

39. (Amended) A method according to Claim 35:
wherein the step of forming the dielectric layer comprises the step of forming a dielectric layer on an integrated circuit substrate, the dielectric layer including the closed via and an open via therein; and
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